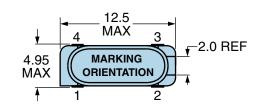
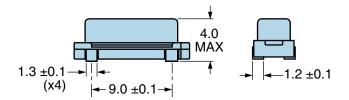


ELECTRICAL SPECIFICATIONS		
Nominal Frequency	14.31818MHz	
Frequency Tolerance/Stability	±30ppm at 25°C, ±50ppm over -40°C to +85°C	
Aging at 25°C	±5ppm/year Maximum	
Load Capacitance	18pF Parallel Resonant	
Shunt Capacitance (C0)	7pF Maximum	
Equivalent Series Resistance	70 Ohms Maximum	
Mode of Operation	AT-Cut Fundamental	
Drive Level	1mWatts Maximum	
Storage Temperature Range	-40°C to +85°C	
Insulation Resistance	500 Megaohms Minimum at 100Vdc	

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014 Condition A	
Gross Leak Test	MIL-STD-883, Method 1014 Condition C	
Mechanical Shock	MIL-STD-202, Method 213 Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007 Condition A	

### **MECHANICAL DIMENSIONS (all dimensions in millimeters)**





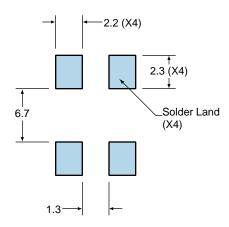
PIN	CONNECTION
1	Crystal
2	Connected to Pin 3
3	Connected to Pin 2
4	Crystal

LINE	MARKING
1	E14.318 E=Ecliptek Designator



### **Suggested Solder Pad Layout**

All Dimensions in Millimeters

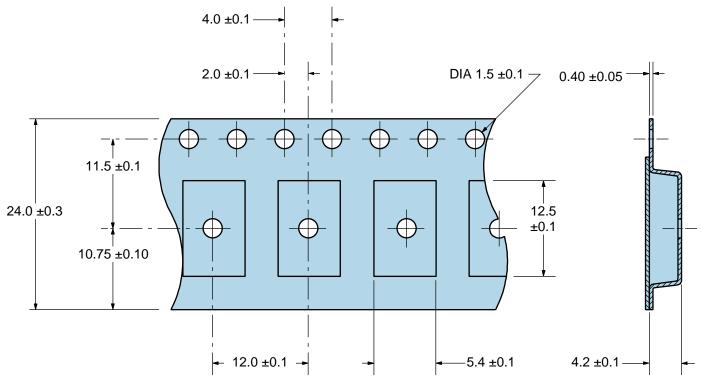


All Tolerances are ±0.1

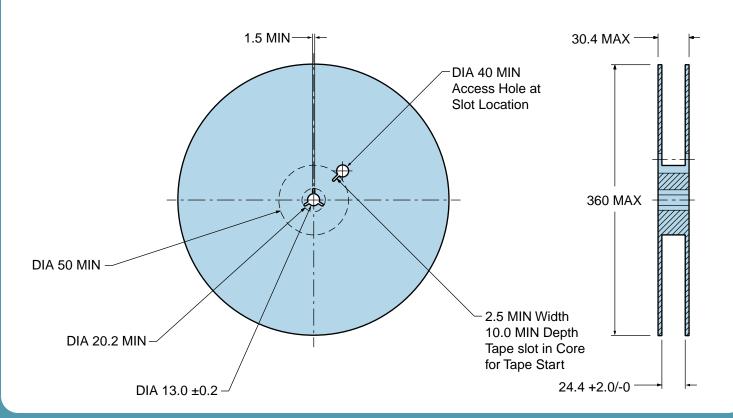


# **Tape & Reel Dimensions**

Quantity Per Reel: 1,000 units



\*Compliant to EIA 481A





## **Recommended Solder Reflow Methods**



### Low Temperature Infrared/Convection 225°C

T <sub>S</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T <sub>s</sub> MIN)	N/A
- Temperature Typical (T <sub>s</sub> TYP)	150°C
- Temperature Maximum (T <sub>s</sub> MAX)	N/A
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T <sub>P</sub> )	225°C Maximum
Target Peak Temperature (T <sub>P</sub> Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (tp)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

#### **Low Temperature Manual Soldering**

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### **High Temperature Manual Soldering**

260°C Maximum for 5 seconds Maximum, 2 times Maximum.